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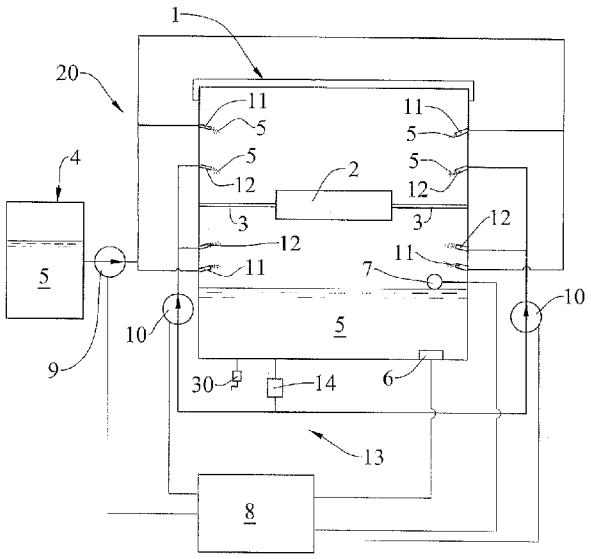
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(54) **Title:** APPARATUS FOR REMOVING OR DECREASING THE RESIN FLUSH FROM THE METALLIC PART OF A SEMICONDUCTOR DEVICE.



(57) **Abstract:** An apparatus for removing or decreasing the resin flush from the top of the metallic part of a semiconductor device is described, comprising a main reservoir and nozzles for sprinkling a solution with abrasive material suspended therein onto a semiconductor device placed in said main reservoir. Said apparatus also comprises a pressure sensor placed at the bottom of said main reservoir, a liquid level sensor associated with said main reservoir and a control unit for feeding said solution to said nozzles according to the pressure and level raised by said sensors.

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